



CED03N100/CEU03N100

N-Channel Enhancement Mode Field Effect Transistor

FEATURES

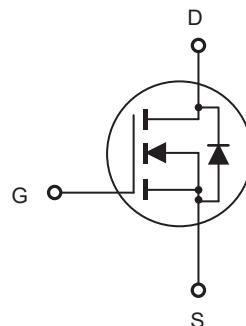
- 1000V, 3A, $R_{DS(ON)} = 6\Omega$ @ $V_{GS} = 10V$.
- Super high dense cell design for extremely low $R_{DS(ON)}$.
- High power and current handing capability.
- Pb-free lead plating ; RoHS compliant.
- Halogen Free.
- TO-251 & TO-252 package.



CEU SERIES
TO-252(D-PAK)



CED SERIES
TO-251(I-PAK)



ABSOLUTE MAXIMUM RATINGS $T_C = 25^\circ C$ unless otherwise noted

Parameter	Symbol	Limit	Units
Drain-Source Voltage	V_{DS}	1000	V
Gate-Source Voltage	V_{GS}	± 30	V
Drain Current-Continuous@ $T_C = 25^\circ C$ @ $T_C = 100^\circ C$	I_D	3 1.9	A
Drain Current-Pulsed ^a	I_{DM}	12	A
Maximum Power Dissipation @ $T_C = 25^\circ C$ - Derate above $25^\circ C$	P_D	111 0.74	W W/ $^\circ C$
Single Pulsed Avalanche Energy ^d	E_{AS}	112	$^\circ mJ$
Single Pulsed Avalanche Current ^d	I_{AS}	3	A
Operating and Store Temperature Range	T_J, T_{stg}	-55 to 175	C

Thermal Characteristics

Parameter	Symbol	Limit	Units
Thermal Resistance, Junction-to-Case	$R_{\theta JC}$	1.35	$^\circ C/W$
Thermal Resistance, Junction-to-Ambient	$R_{\theta JA}$	50	$^\circ C/W$



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Electrical Characteristics $T_C = 25^\circ\text{C}$ unless otherwise noted

Parameter	Symbol	Test Condition	Min	Typ	Max	Units
Off Characteristics						
Drain-Source Breakdown Voltage	BV_{DSS}	$V_{\text{GS}} = 0\text{V}, I_D = 250\mu\text{A}$	1000			V
Zero Gate Voltage Drain Current	I_{DSS}	$V_{\text{DS}} = 1000\text{V}, V_{\text{GS}} = 0\text{V}$		1		μA
Gate Body Leakage Current, Forward	I_{GSSF}	$V_{\text{GS}} = 30\text{V}, V_{\text{DS}} = 0\text{V}$		100		nA
Gate Body Leakage Current, Reverse	I_{GSSR}	$V_{\text{GS}} = -30\text{V}, V_{\text{DS}} = 0\text{V}$		-100		nA
On Characteristics^b						
Gate Threshold Voltage	$V_{\text{GS}(\text{th})}$	$V_{\text{GS}} = V_{\text{DS}}, I_D = 250\mu\text{A}$	3		4	V
Static Drain-Source On-Resistance	$R_{\text{DS}(\text{on})}$	$V_{\text{GS}} = 10\text{V}, I_D = 1.5\text{A}$		4.8	6	Ω
Dynamic Characteristics^c						
Input Capacitance	C_{iss}	$V_{\text{DS}} = 25\text{V}, V_{\text{GS}} = 0\text{V}, f = 1.0 \text{ MHz}$		485		pF
Output Capacitance	C_{oss}			75		pF
Reverse Transfer Capacitance	C_{rss}			25		pF
Switching Characteristics^c						
Turn-On Delay Time	$t_{\text{d}(\text{on})}$	$V_{\text{DD}} = 500\text{V}, I_D = 3\text{A}, V_{\text{GS}} = 10\text{V}, R_{\text{GEN}} = 10\Omega$		23		ns
Turn-On Rise Time	t_r			18		ns
Turn-Off Delay Time	$t_{\text{d}(\text{off})}$			50		ns
Turn-Off Fall Time	t_f			18		ns
Total Gate Charge	Q_g	$V_{\text{DS}} = 800\text{V}, I_D = 1\text{A}, V_{\text{GS}} = 10\text{V}$		25		nC
Gate-Source Charge	Q_{gs}			2		nC
Gate-Drain Charge	Q_{gd}			14		nC
Drain-Source Diode Characteristics and Maximum Ratings						
Drain-Source Diode Forward Current	I_S				3	A
Drain-Source Diode Forward Voltage ^b	V_{SD}	$V_{\text{GS}} = 0\text{V}, I_S = 3\text{A}$			1.4	V

Notes :

- a.Repetitive Rating : Pulse width limited by maximum junction temperature.
- b.Pulse Test : Pulse Width $\leq 300\mu\text{s}$, Duty Cycle $\leq 2\%$.
- c.Guaranteed by design, not subject to production testing.
- d.L = 25mH, $I_{AS} = 3\text{A}$, $V_{DD} = 50\text{V}$, $R_G = 25\Omega$, Starting $T_J = 25^\circ\text{C}$

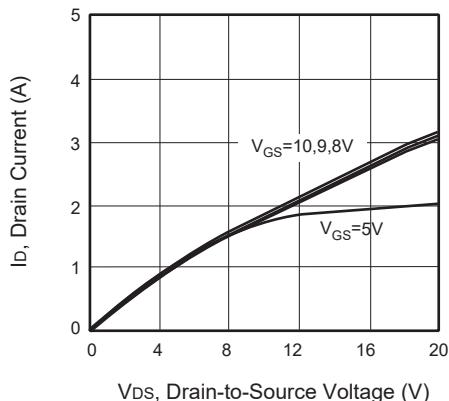


Figure 1. Output Characteristics

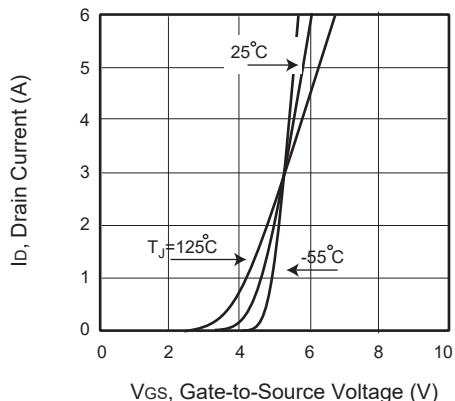


Figure 2. Transfer Characteristics

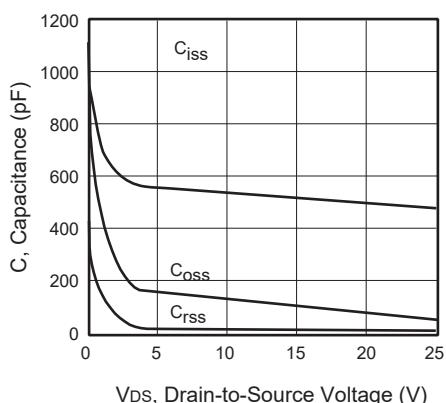


Figure 3. Capacitance

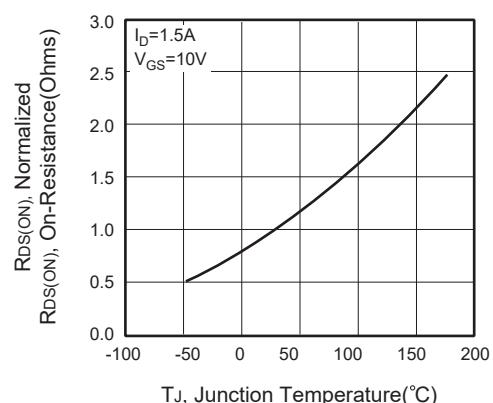


Figure 4. On-Resistance Variation with Temperature

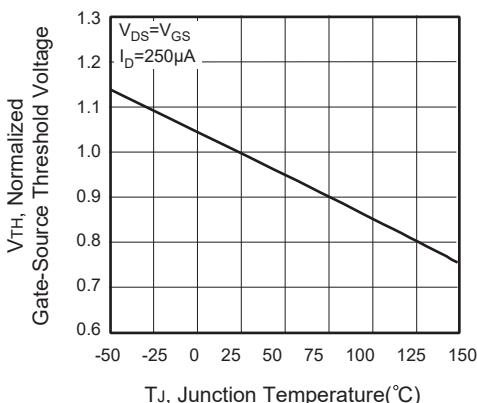


Figure 5. Gate Threshold Variation with Temperature

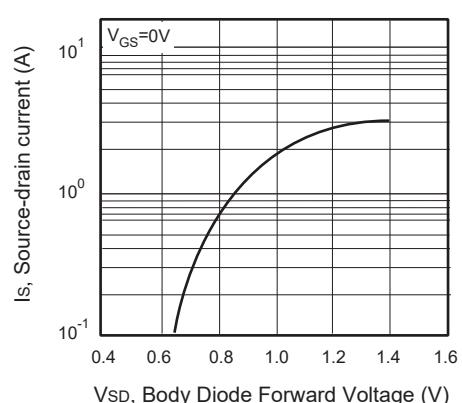


Figure 6. Body Diode Forward Voltage Variation with Source Current



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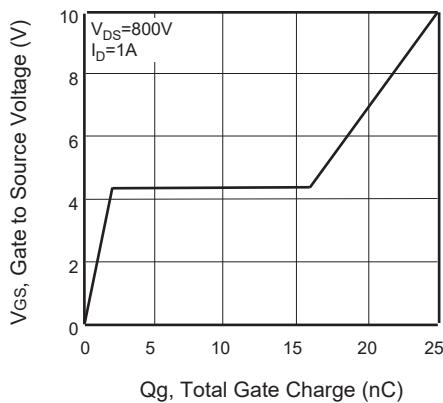


Figure 7. Gate Charge

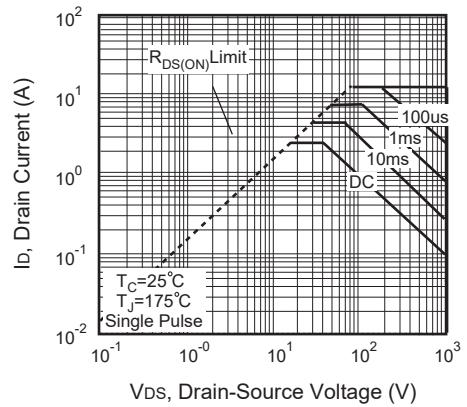


Figure 8. Maximum Safe
Operating Area

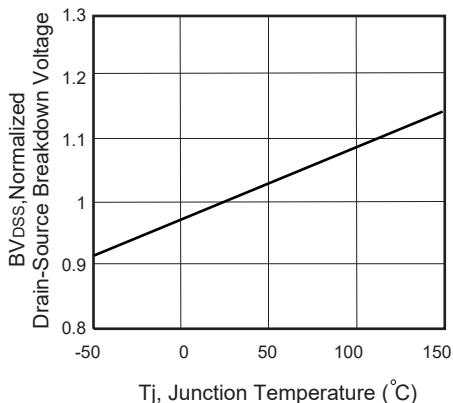


Figure 9. Breakdown Voltage Variation
VS Temperature

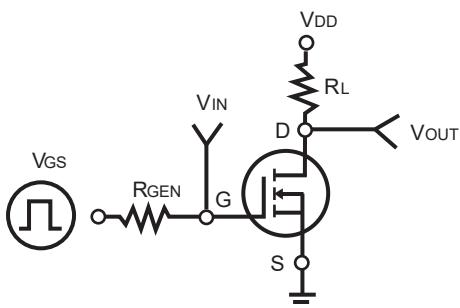


Figure 10. Switching Test Circuit

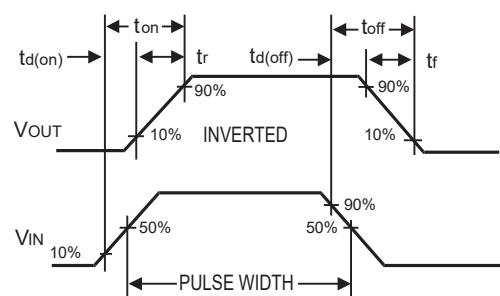


Figure 11. Switching Waveforms



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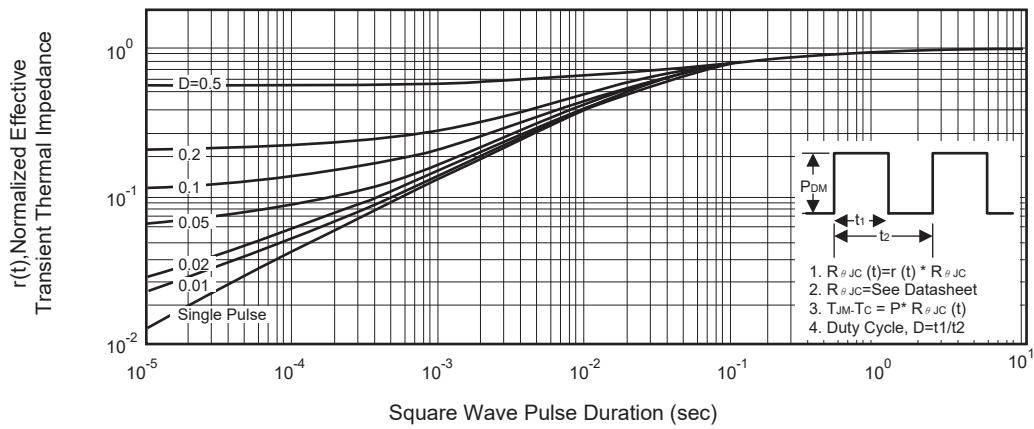


Figure 12. Normalized Thermal Transient Impedance Curve